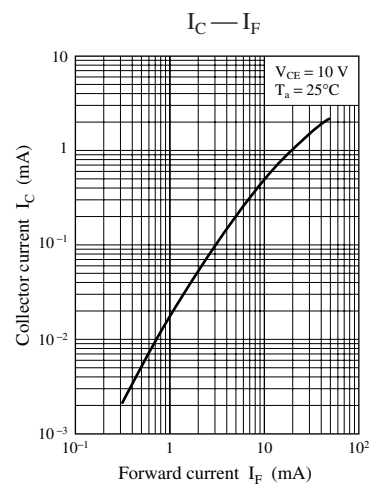
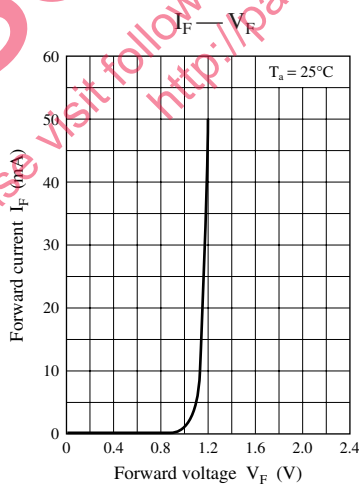
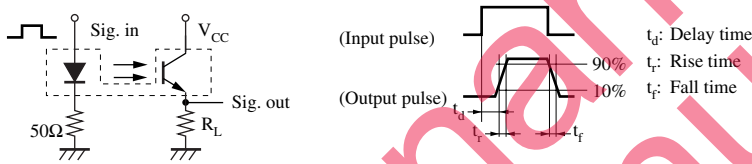


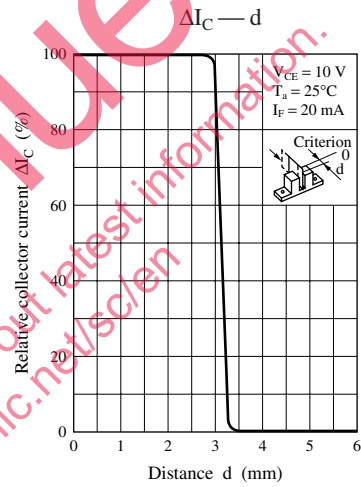
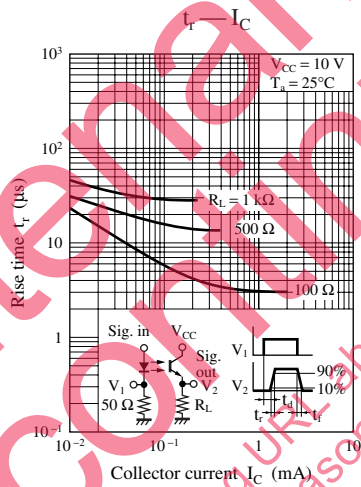
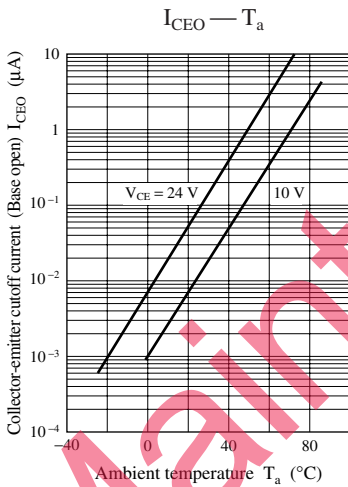
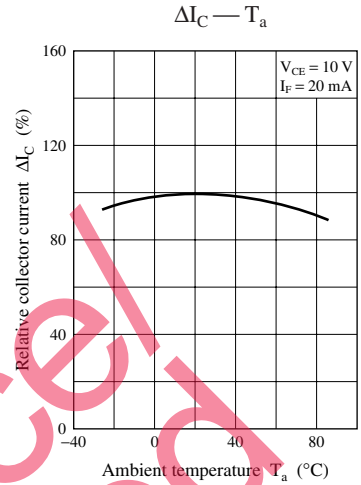
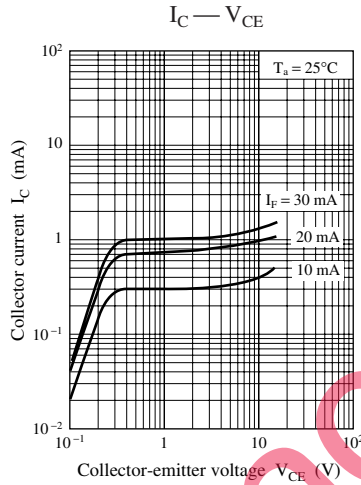
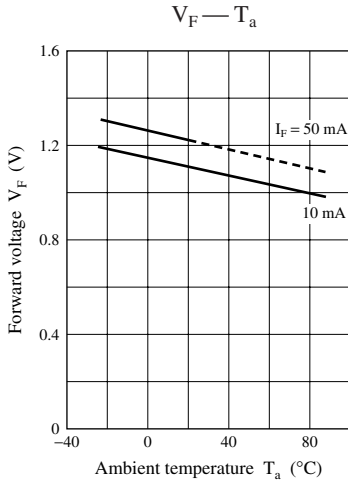


■ Electrical-Optical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

	Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Input characteristics	Forward voltage	$V_F$	$I_F = 50\text{ mA}$		1.2	1.5	V
	Reverse current	$I_R$	$V_R = 3\text{ V}$			10	$\mu\text{A}$
Output characteristics	Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 10\text{ V}$			200	nA
	Collector-emitter capacitance	$C_C$	$V_{CE} = 10\text{ V}, f = 1\text{ MHz}$		5		pF
Transfer characteristics	Collector current	$I_C$	$V_{CE} = 10\text{ V}, I_F = 20\text{ mA}$	0.3			mA
	Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_F = 50\text{ mA}, I_C = 0.1\text{ mA}$			0.3	V
	Rise time *	$t_r$	$V_{CC} = 10\text{ V}, I_C = 1\text{ mA}, R_L = 100\ \Omega$		6.0		$\mu\text{s}$
	Fall time *	$t_f$			6.0		$\mu\text{s}$

- Note) 1. Input and output are practiced by electricity.  
 2. This device is designed by disregarded radiation.  
 3. \*: Switching time measurement circuit





# Caution for Safety

 **DANGER**

## ■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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  - Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
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